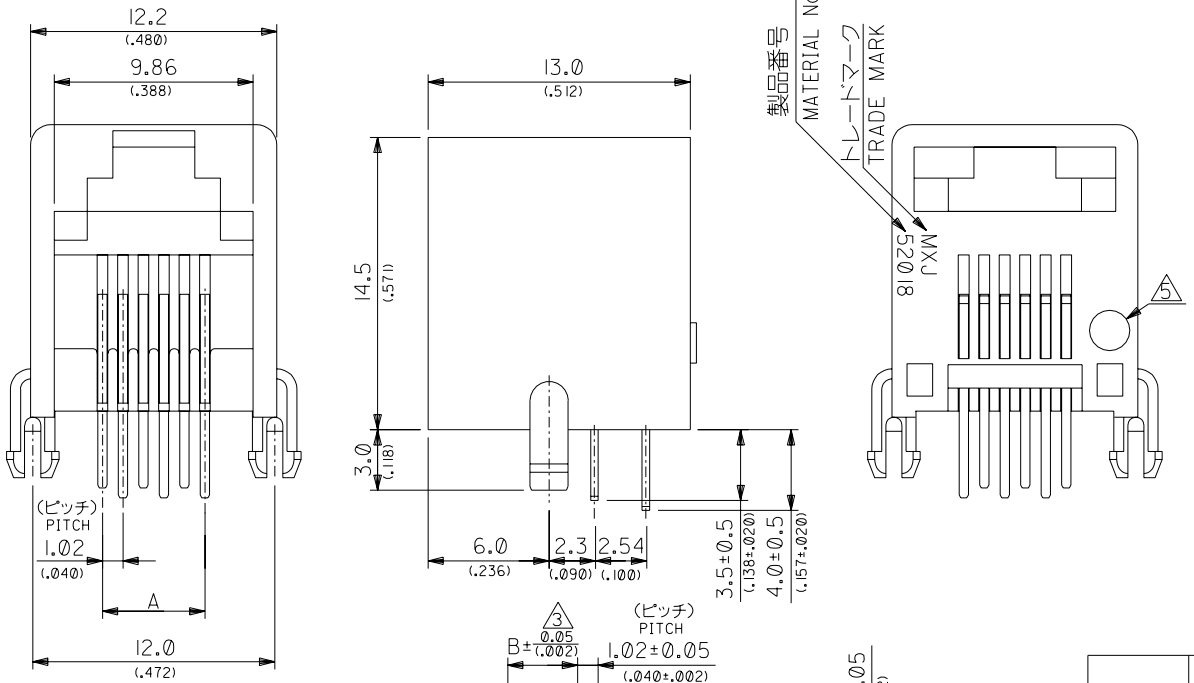
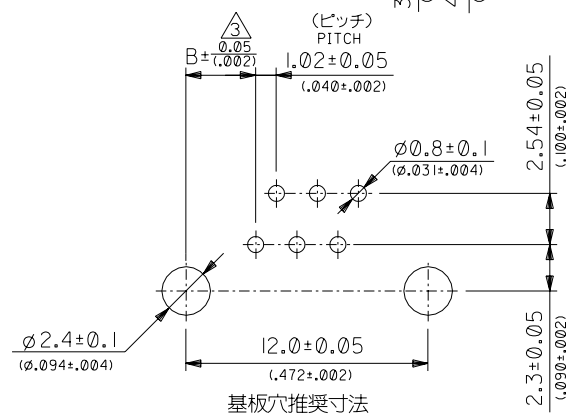
DWG. NO. SD-52018-003



注) NOTES

1. 材質 MATERIAL
   ハウジング：ガラス入リポリエステル UL94V-0
   HSG. :POLYESTER G.F.15% UL94V-0
   ターミナル：リン青銅
   TERM. :PHOSPHOR BRONZE
2. メッキ仕様 PLATING
   接点部 ：金メッキ、表参照
   CONTACT AREA: GOLD PER TABLE
   半田付け部：錫メッキ 1.0μmMIN.
   SOLDER AREA : TIN 1.0 MICROMETER MINIMUM.
   下地メッキ：ニッケルメッキ 1.0μmMIN.
   UNDERPLATE : NICKEL 1.0 MICROMETER MINIMUM.
3. −64＊6は両端の基板穴を除く。
   −62＊6は両端の2つの基板穴を除く。
   DIM B INDICATES FIRST P.C.HOLE
   REQUIRED PER PART NUMBER.
   FOR PARTIALLY LOADED ASSEMBLIES
   P.C.HOLE PATTERN IS REDUCED FROM EACH END.
4. 推奨基板厚：t＝1.6±0.05
   RECOMMENDED P.C.B. THICKNESS: 1.6±0.05
5. 金メッキ厚標示
   COLOR CODING TO INDICATE GOLD PLATING
   黄色：0.1μmMIN. YELLOW : 0.1 MICROMETER MINIMUM.
   緑色：0.38μmMIN. GREEN : 0.38 MICROMETER MINIMUM.
   オレンジ色：0.76μmMIN. ORANGE : 0.76 MICROMETER MINIMUM.
   無色：1.27μmMIN. UNMARKED: 1.27 MICROMETER MINIMUM.
6. ハウジングの色は、グレイ。
   HOUSING COLOR IS GRAY.
7. 本製品は52018−6＊＊5の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 52018-6**5.



基板穴推奨寸法

RECOMMENDED P.C.B. LAYOUT
(ジャック取付け側)
(JACK ASS'Y SIDE)

ポジション POSITION	極数 CIRCUITS	A	B	金メッキ厚 μm/(μMIN) GOLD PLATING THK(MIN.) μm/(μMIN)	製品番号 MATERIAL No.
6	6	5.08 (.200)	3.46 (.136)	1.27 / (50)	52018-6646
				0.76 / (30)	-6636
				0.38 / (15)	-6626
				0.1 / (4)	-6616
6	4	3.05 (.120)	4.48 (.176)	1.27 / (50)	-6446
				0.76 / (30)	-6436
				0.38 / (15)	-6426
				0.1 / (4)	-6416
6	2	1.02 (.040)	5.49 (.216)	1.27 / (50)	-6246
				0.76 / (30)	-6236
				0.38 / (15)	-6226
				0.1 / (4)	52018-6216

MODEL NO. 52018-6**6

DIMENSIONS: ☐ mm/INCH ☐ INCH/mm ☒ mm ONLY

SHT REV

DO NOT SCALE DRAWING

234NO. DRWN: CH'K: APPR:	233NO. DRWN: CH'K: APPR:	232NO. DRWN: CH'K: APPR:	231NO. DRWN: CH'K: APPR:	新規作成 RELEASED 230NO.J2004-4221 DRWN:M.NAGATA '04/05/14 CH'K:K.TOJO '04/05/14 APPR:M.SASAO '04/05/14	DESCRIPTION
				0	REV

MATERIAL 材料: 注参照 SEE NOTES

FINISH 仕上げ: 注及び表参照 SEE NOTES AND CHART

WIRE RANGE 適用電線範囲: —#—

INS. RANGE 被覆外径: —#—

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差

10 (.394) UNDER 未満		±0.2 (.008)
10 (.394) OVER 以上	30 (1.181) UNDER 未満	±0.25 (.010)
30 (1.181) OVER 以上		±0.3 (.012)
ANGLE 角度		±3°

SCALE 4:1

DESIGN UNITS ☒mm ☐INCH

THIRD ANGLE PROJECTION

DRAWN BY & DATE M.NAGATA '04/05/14

CHECKED BY & DATE K.TOJO '04/05/14

APPROVED BY & DATE M.SASAO '04/05/14

CAD FILENAME SD-52018-003.S01

TITLE: MODULAR JACK HOUSING ASS'Y -LEAD FREE-

molex MOLEX INCORPORATED

MATERIAL NO. SEE CHART

DRAWING NO. SD-52018-003

SHEET NO. 1 OF 1

SIZE B

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EN-02J(097) MXJ-54